

JP09092775

SEMICONDUCTOR DEVICE

HITACHI CABLE LTD

Inventor(s): ;OTAKA TATSUYA ;HATANO KAZUHISA ;MURAKAMI HAJIME
;YONEMOTO TAKAHARU ;YOSHIOKA OSAMU

Application No. 07244204 , Filed 19950922 , Published 19970404

Abstract:

PROBLEM TO BE SOLVED: To make a package small in thickness in a CSP (Chip Scale Package) structure by which a lead frame of the same size is mounted on a semiconductor chip.

SOLUTION: A lead frame 4 to be adhered to a semiconductor chip 1 is almost the same in size as the chip 1. The surface 4e of an inner lead 4a of the lead frame 4 is coined to form a coined part 5 with reduced thickness. The lead frame 4 and the end surface 1c of the chip 1 are adhered to each other with a double-faced adhesive tape 3 interposed. The coined part 5 of the inner lead 4a is connected with a bonding pad 2 of the chip 1 through a bonding wire 9. The surface 1a of the chip 1 is packaged with a mold resin 8, thereby exposing only the surface 4c of an outer lead 4b on the packaged resin surface 8a.

Int'l Class: H01L02350

MicroPatent Reference Number: 000907573

COPYRIGHT: (C) 1997 JPO

